

ELECTRONIC INDUSTRY

ADHESIVES | SEALANTS | COATINGS



KOHESI BOND

Custom Engineered Adhesives

Kohesi Bond is a pioneer in manufacturing custom engineered adhesives, sealants, coatings, potting and encapsulation compounds. We offer a sweeping range of first-rate epoxy systems designed specifically for use in semiconductor packaging and assembly of electronics such as printed circuit boards.

Using our extensive technical expertise, we offer these formulations with an array of performance and curing characteristics. Our unique ability to tailor products to each application's specific needs, offers customers with reliable solutions and the ease of manufacturing. Product's mechanical strength, hardness, temperature resistance, viscosity, resistance to chemicals, heat dissipation, electrical conductivity and many other properties can be fitted through custom formulations. They can also be color matched precisely to the user's needs.

Through consistent quality, technical know-how and groundbreaking innovation, Kohesi Bond has proven to deliver complete solutions to today's growing electronic industry.

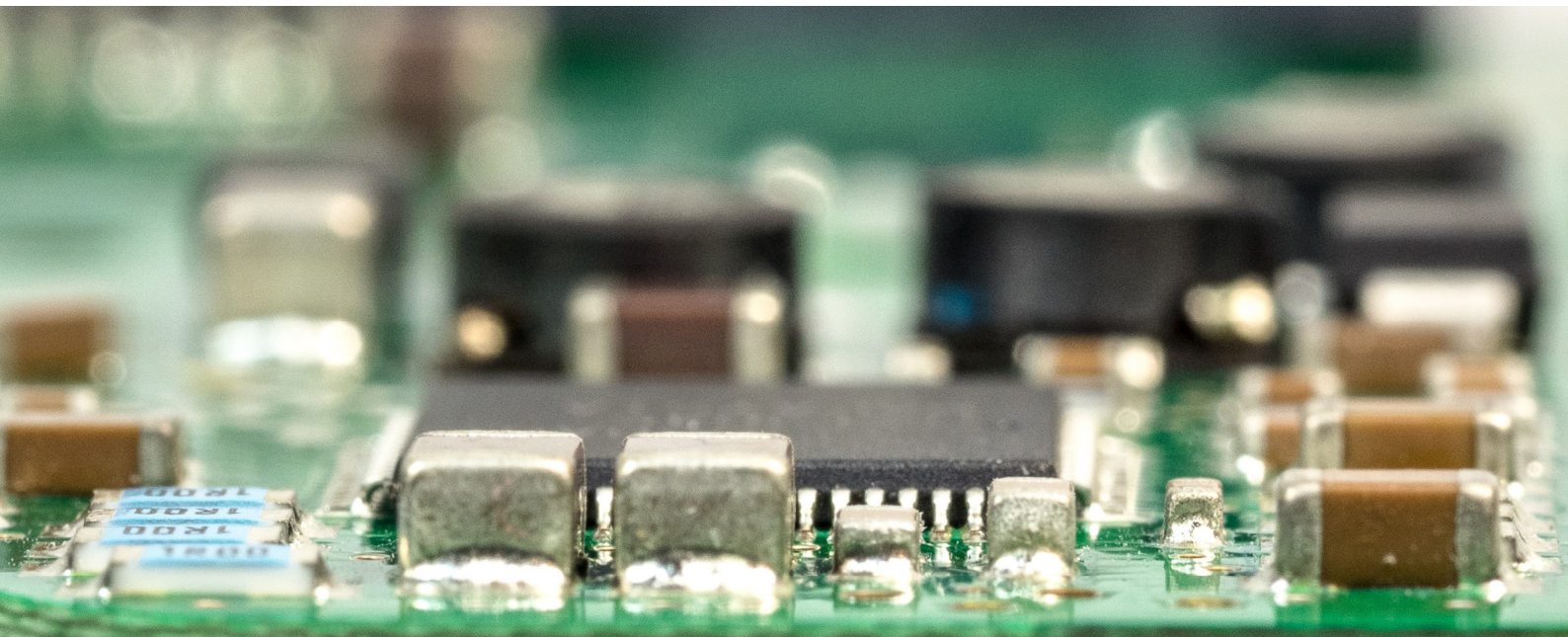


Innovation tailored to **your** needs

Kohesi Bond performance products are specially designed for successful use in your applications from initial prototyping to scaled-up production lines. Meeting new challenges of the electronic industry means inventing new technology. To make this happen, we offer you round-the-clock assistance right from the research and design phase through the manufacturing process.

Typical Applications

- Chip & Wire Bonding
- Conformal Coating
- Die-attach
- EMI/RFI Shielding
- Glob Top
- Potting & Encapsulation
- Printed Circuit Board Assembly
- Thermal Management
- Underfill
- Surface Mount



LIST OF PRODUCTS

Product	Electrically Conductive	Electrically Insulative	Thermally Conductive	Bonding/ Sealing	Coating	Potting/ Encapsulation	Page No.
ONE COMPONENT EPOXIES							
KB 1613 HT		√		√			1
KB 1613 RLV		√	√			√	1
KB 1613 R80		√	√	√		√	1
KB 1427 HT		√		√		√	2
KB 1427 HT-3		√		√		√	2
TUF 1613 HT-DA		√	√	√			3
TUF 1613 HT-CM		√	√		√	√	3
TUF 1613 HT-GT		√	√	√			4
TUF 1613 HT-SM		√	√	√			4
TUF 1820 AOHT		√	√	√			4
TUF 1820 ANHT		√	√	√			5
TUF 1820 HTS	√		√	√			5
TUF 1828 TC		√	√	√			5
TWO COMPONENT EPOXIES							
KB 1631 AOLV-1		√	√	√	√		6
KB 1631 HTC-1		√	√	√			6
KB 1631 FR-2		√				√	6
KB 1031 AT-2LO		√	√	√		√	7
KB 1031 ATHT-LO		√		√			7
KB 1031 ATFL-N	√		√	√			7
KB 1031 AT-S	√		√	√			8
KB 1031 SPLV-6				√	√	√	8
KB 1631 ANHT		√	√	√	√		8
KB 1040-2		√		√	√	√	9
KB 1040 AN-1		√	√	√	√	√	9
KB 1040 P		√		√	√	√	9

LIST OF PRODUCTS

Product	Electrically Conductive	Electrically Insulative	Thermally Conductive	Bonding/ Sealing	Coating	Potting/ Encapsulation	Page No.
TWO COMPONENT EPOXIES (continued)							
KB 1040 CTE-LO		✓	✓	✓	✓	✓	10
KB 1040		✓		✓	✓	✓	10
KB 1040 QF		✓		✓	✓	✓	10
KB 1039 CRLP		✓		✓	✓	✓	11
KB 1039 CRLP-AO		✓	✓	✓	✓	✓	11
KB 10473 FL		✓		✓	✓	✓	11
KB 10473 FLAO		✓	✓	✓	✓	✓	12
KB 1048		✓	✓	✓	✓	✓	12
KB 1151 S-1		✓		✓	✓	✓	12
KB 1452 HT-2		✓		✓	✓	✓	13
KB 1372-LO		✓		✓	✓		13
KB 1085-1	✓		✓	✓	✓		13
KB 1686 M	✓		✓	✓	✓		14
KB 1689	✓		✓	✓			14
TUF 1621 AOHT		✓	✓	✓	✓		14
TUF 1452 HT-2		✓		✓	✓	✓	15
KB 1040 AOHT		✓		✓	✓	✓	15
KB 1452 HT-2AO		✓	✓	✓	✓	✓	15
KB 1458 TC		✓	✓	✓			16
KB 1600 FR-V		✓		✓	✓	✓	16
KB 1372-AO		✓	✓	✓	✓		17
KB 1372 LP		✓		✓	✓	✓	17
SODIUM SILICATES							
KB-SS-SIL	✓				✓		18
KB-SS-SCN	✓				✓		18
KB-SS-G	✓				✓		18